

Specification	AXIS45SH	Rev.: 1	Date: 2025-02-10
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Oscillator type: Low Phase Noise 10~200 MHz VCXO for Space Application (Space COTS version)

Features:

- Lower cost New Space version (COTS)
- Manufactured according to MIL-PRF-55310 Level "S"
- Radiation hardened – 40 krad(Si) total dose (TID)
- Radiation hardened – SEL immunity / SET insensitive
- VCXO Characteristic can be tailored to customer requirements
- ITAR Free – Manufactured in Germany
- Low Phase Noise
- Hermetical sealed THD package



Models:

Item	Engineering Model (EM)	Flight Model (FM)	Note
Quartz Crystal	Synthetic HiQ Quartz, AT-cut, HC-52/U	Synthetic HiQ Quartz, AT-cut, HC-45/U	1
Electrical Components	COTS parts	COTS parts Automotive Grade and/or HighRel Heritage	2
Mechanical Components	Stainless steel package with Ni finish	Stainless steel package with Ni finish	-
Workmanship (Soldering)	IPC610 Class 3	IPC610 Class 3	-
Rad Hardness	-	40 krad(Si) TID	3
Acceptance Testing			
Screening	Test procedure as commercial models	X	4
Group-B		X	-
Group-C	-	On request	5

Notes:

1. Swept Quartz material available on request.
2. Higher product levels of add-on components on request. For tin whisker mitigation components with SnPb finish can be used on request.
3. Semiconductors tested up to 50 krad and SEE tested up to 60 MeV-cm²/mg
4. Screening procedure can be modified IAW customer requirements.
5. Group-C (LAT) can be performed based on customer requirements.

Ordering Code:

Model	Product category	Option 1	Revision	Frequency [MHz]
AXIS45SH	EM FM	"33" – 3.3 V Supply "50" – 5.0 V Supply	Rev.1	100.000

Example: AXIS45SH-FM-50_Rev.1 – 100.000 MHz

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1. Electrical specification

Parameter	min.	typ.	max.	Unit	Condition
Frequency range 1 (Note 4)	10		100	MHz	Crystal frequency
Frequency range 2 (Note 4)	>100		200	MHz	Multiplication
Frequency stability					
vs. operating temperature range		±10	±15	ppm	ref. to f_{nominal}
vs. supply voltage variation (pushing)			±0.5	ppm	$V_s \pm 5\%$
vs. load change (pulling)			±0.5	ppm	$R_L \pm 5\%$
Long term (aging) 1 st year			±1	ppm	after 30 days operation
Long term (aging) over 10 years			±4	ppm	after 30 days operation
Frequency adjustment range					
Electronic Frequency Control (EFC)	±20	±30		ppm	(Note 3)
EFC voltage V_c	0	2.5	5.0	V	Option 1 = "33"
	0	1.5	3.3	V	Option 1 = "50"
EFC slope ($\Delta f / \Delta V_c$)	Positive				
EFC input impedance	100			k Ω	
EFC non-linearity		5	10	%	
RF output					
Signal waveform	Sine wave				
Load R_L	50			Ω	±5%
Output level	+4	+7	+10	dBm	Frequency range 1
	+7	+9	+12	dBm	Frequency range 2
Harmonics		-40	-30	dBc	
Sub-harmonics		-50	-40	dBc	Frequency range 2 only
Spurious			-90	dBc	
Phase noise	Consult factory See performance examples				
Supply voltage V_s	3.15	3.3	3.45	V	Option 1 = "33"
	4.75	5.0	5.25	V	Option 1 = "50"
Current consumption			20	mA	Frequency range 1
			40	mA	Frequency range 2
Operating temperature range	-30		+70	°C	

Table 1 – Electrical Performance and Characteristics

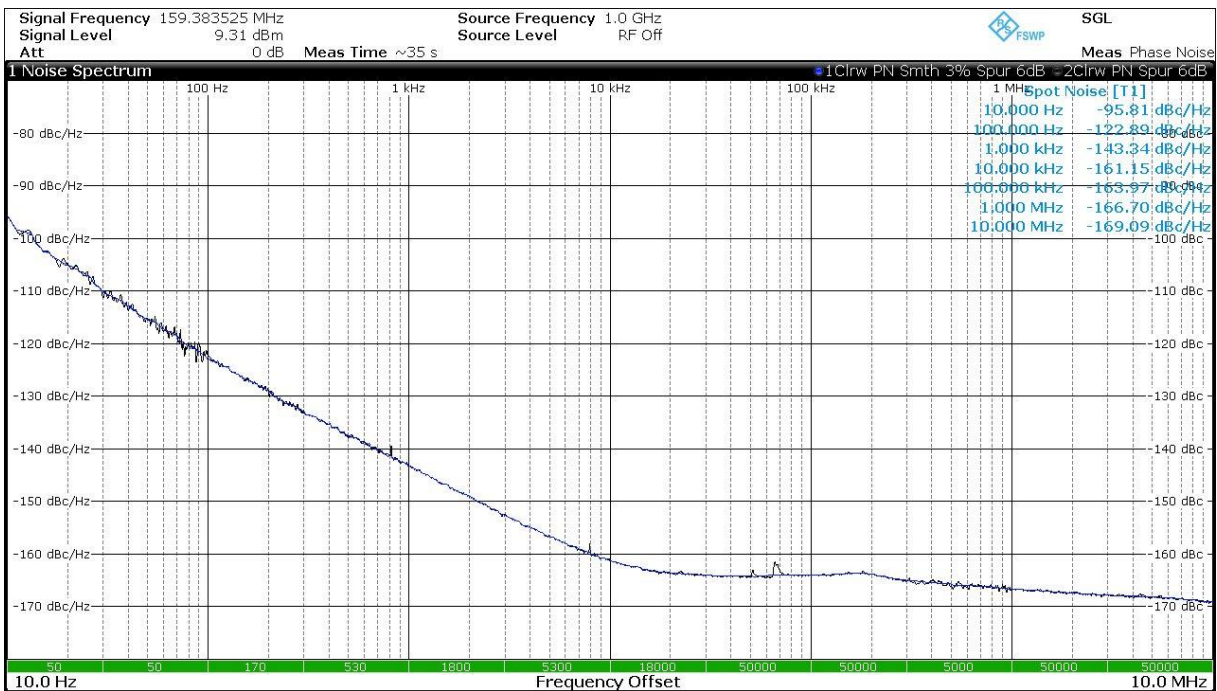
Notes:

1. Terminology and test conditions are according to IEC60679-1 and MIL-PRF-55310 unless otherwise stated
2. Classification (MIL-PRF-55310): Type 2 (VCXO), Class 1 (Discrete Technology), Product Level "S"
3. Tuning range is sufficient to compensate temperature stability, pushing, pulling, aging over 10 years and change due to radiation.
4. The entire VCXO characteristic including frequency, supply voltage and tuning characteristic can be tailored to customer requirements. Multiplication of frequencies < 100 MHz can be used to increase tuning range and to improve close-in phase noise. Please consult factory.

Phase noise – Performance examples



100 MHz



160 MHz

Absolute Maximum Ratings

Parameter	Min.	Max.	Unit	Condition / Remark
Supply Voltage V_s	-0.5	$V_s + 10\%$	V	V_s to GND
Control Voltage V_c	-0.5	15	V	V_s to GND
Load R_L	0	∞	Ω	Must not cause any damage
Operable temperature range	-40	+85	$^{\circ}\text{C}$	Operation of unit without any damage
Storage temperature range	-55	+105	$^{\circ}\text{C}$	-

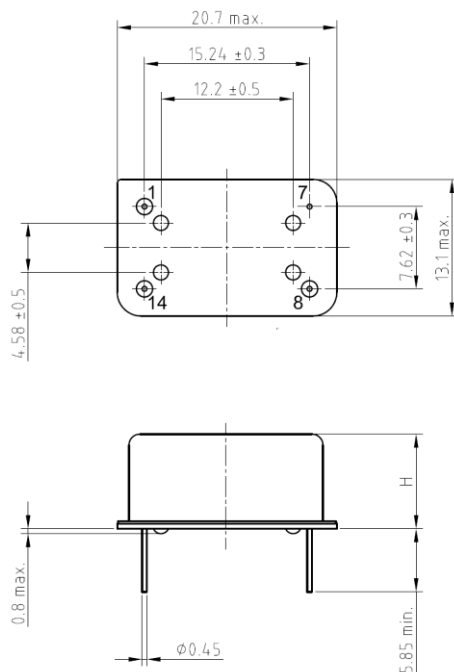
Table 2 – Maximum Ratings

2. Mechanical specification

Parameter	Min.	Typ.	Max.	Unit	Condition
Enclosure (see drawing) (LxWxH)	20.7x13.1x7.5 max.			mm	IEC 60679-3 CO 02
Weight			5	g	
Case material	Stainless steel			-	
Case finish	Cover: Stainless steel blank Header: Ni 8 μm			-	
Pins	Glass / Kovar Solder dipped			-	EM: RoHS FM: Sn63Pb37

Table 3 – Mechanical specification

Enclosure drawing



Pin connections

Pin #	Symbol	Function
1	V_c	Control Voltage (EFC)
7	GND	Ground
8	RF OUT	RF Output
14	V_s	Supply Voltage

3. Applicable documents

The following specifications and standards are part of this specification:

IPC-A-610	Acceptability of electronic assemblies
ESCC21300	Terms, Definitions, Abbreviations, Symbols and Units
ESCC21700	General Requirements for the marking of ESCC components
MIL-STD-55310	General specification for crystal-controlled oscillators
MIL-STD-202	Test Method Standard for electronic and electrical component parts
MIL-STD-883	Test Method Standard for Microcircuits
IEC 60679-1	Quartz crystal-controlled oscillators of assessed quality Part 1: Generic specification

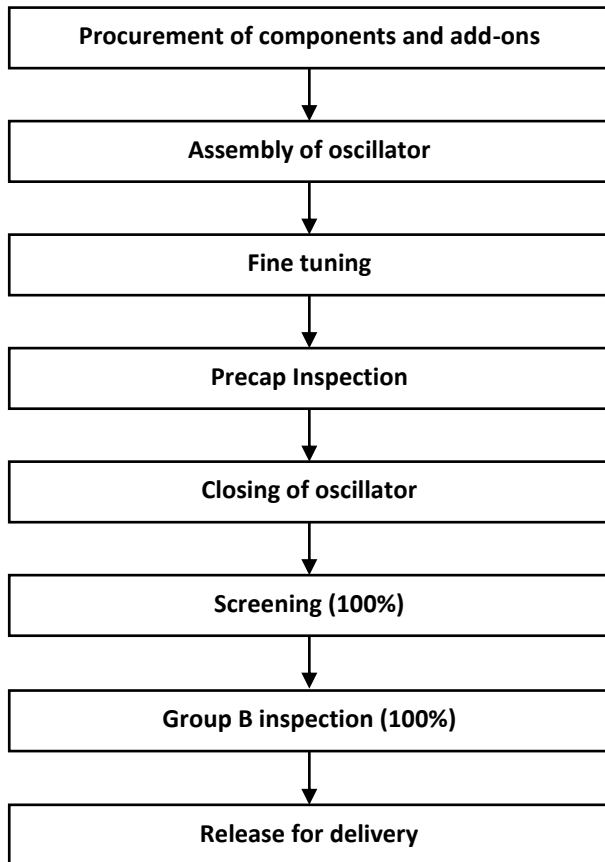
Order of precedence

In the event of a conflict between the text of this specification and the references cited herein, the order of precedence shall be as follows:

- (1) Purchase order
- (2) Oscillator detail specification AXIS45SH
- (3) Generic specification MIL-PRF-55310
- (4) Other documents

4. General flow of manufacturing

The figure below shows the overall flow for manufacturing:



5. Acceptance Testing

5.1 Screening

Table 4 shows the screening procedure according to MIL-PRF-55310 Product level "S".

#	Test	Reference
1	Electrical measurements at room temperature (Initial)	IEC 60679-1 (see Table 1)
2	Thermal Shock	MIL-STD-202, Method 107, Condition A-1
3	Burn-in (load) ^{*1}	MIL-PRF-55310
4	Seal Test – Gross Leak	MIL-STD-202, Method 112, Condition D
5	Electrical measurements vs. temperature	IEC 60679-1 (see Table 1)
6	Electrical measurements at room temperature (Final)	IEC 60679-1 (see Table 1)
7	External Visual Inspection	ESCC20500 / MIL-STD-883 Method 2009

Table 4 – Screening procedure

Notes:

1. Burn-in can be performed at any step after assembly and is usually performed as pre-aging procedure

Table 5 shows the detailed test conditions for each step in table 4.

#	Test	Test Condition
1	Electrical measurements at room temperature (Initial)	@ T _{amb} = 25°C±3°C (unless otherwise stated) Table 8
2	Thermal Shock	-40 to +80°C, 25 cycles, max. 5 minutes transfer time, 15 minutes dwell time
3	Burn-in (load)	@ T = +85°C for 10 days (nominal V _s and Load)
4	Seal Test – Gross Leak	No bubbles allowed
5	Electrical measurements vs. temperature	@ T = -30 to +70°C, 10°C steps with ±1°C tolerance Limits: See Table 1
6	Electrical measurements at room temperature (Final)	@ T _{amb} = 25°C±3°C (unless otherwise stated) Table 8
7	External Visual Inspection	ESCC20500 / MIL-STD-883 Method 2009

Table 5 – Detailed test conditions for screening procedure

5.2 Group B inspection (Aging)

Table 6 shows the Group B inspection procedure.

#	Test	Reference
1	Aging test	MIL-PRF-55310, Clause 4.7.1.5 Product level "S"
2	Electrical measurements at room temperature (Final)	IEC 60679-1 (see Table 1)

Table 6 – Group B inspection procedure

Notes:

1. Group B inspection may be performed before or after screening procedure. Final electrical measurements are only performed once after completion of screening and Group B inspection.

Table 7 shows the detailed test conditions for each step in table 6.

#	Test	Test Condition
1	Aging test	@ T _{amb} = 30°C±3°C for 30 days (nominal V _s and Load) Frequency measurement every hour Limits Aging: See Table 1
2	Electrical measurements at room temperature (Final)	@ T _{amb} = 25°C±3°C (unless otherwise stated) Table 8

Table 7 – Detailed test conditions for Group B inspection procedure

5.3 Electrical measurements

Table 8 shows all electrical measurements with its respective conditions and limits, which are performed for all models. If not otherwise stated all measurements are performed at T_{amb} = 25°C ± 3°C and after a sufficient stabilization time.

#	Parameter	Test Method	Conditions	Initial	Final	Limits
1	Initial frequency	IEC 60679-1	V _s = 3.3 V, R _L = 50 Ω	X	X	Table 1
2	Tuning range	IEC 60679-1	V _s = 3.3 V, R _L = 50 Ω	X	X	Table 1
3	Output level & spectrum	IEC 60679-1	V _s = 3.3 V, R _L = 50 Ω	X	X	Table 1
4	Current consumption	IEC 60679-1	V _s = 3.3 V, R _L = 50 Ω	X	X	Table 1
5	Phase noise	IEC 60679-1	V _s = 3.3 V, R _L = 50 Ω	-	X	Table 1

Table 8 – Electrical measurements

6. Radiation

The oscillator is capable of meeting all electrical performance requirements after exposure to a total ionizing dose (TID) of 40 krad(Si). The OCXO is based on a Space COTS approach, where the OCXO design incorporates only bipolar technology for the active components, making the OCXO SEL immune.

7. Components, Materials and Processes

The FM models are built on the basis of the following requirements for components, materials and processes:

- All add-on components are specially-selected commercial off-the-shelf (COTS) or higher-grade types. The used active components are automotive qualified in accordance with AEC-Q100/200 and/or have a long HighRel heritage (>10 years, several thousand pieces, no failure) in many products with MIL-PRF-55310 Product Level "B" or "S".
- The active components are radiation hardened based on TID radiation tests made on oscillator level.
- The crystal is made of synthetic high Q quartz material with low inclusion density and low etch channel density (according to IEC 60758). The quartz crystal has a hermetically sealed package.
- Soldering is done in accordance with IPC-A-610 Class 3
- No pure tin is used for the package leads. Soldering of the COTS components is done with Sn63Pb37 solder.
- The printed circuit board (PCB) is commercially procured.
- The marking is resistant to Zestron VD, Isopropyl alcohol (99% pure) and Ethyl alcohol (99.5% pure), tested in accordance with ESCC24800.

8. Marking

The marking of the parts is accordance with ESCC21700. The content is as follows:

- (1) Company Logo AXTAL
- (2) Part number AXTAL (according to order code)
- (3) Part number Customer (on request)
- (4) Nominal frequency
- (5) Serial number
- (6) Date Code

9. Data Documentation

General

With each delivery the following data documentation package is supplied:

- (1) Certificate of Conformity (CoC)
- (2) Test data (full report of all inspections)

The following additional documents can be delivered on request:

- Declared Component List
- Equipment list (Testing & Measuring)
- Product Reliability Analysis (MTBF calculation)
- Radiation Report

Certificate of Conformity

The certificate includes the following content:

- Full company information (Logo, Name, Address)
- Type and specification (part number and revision)
- Nominal frequency
- Number of purchase order
- Lot identification
- Range of serial numbers
- Number of delivered parts
- Authorized signature in behalf of manufacturer (including stamp and date)

10. Handling, Packaging and Delivery

- Some add-ons are susceptible to damage by electrostatic discharge. Therefore, suitable ESD precautions for handling during use and manufacturing must be employed.
- In order to minimize the risk of damage, all kinds of shock during handling and manufacturing must be avoided.
- The parts are packaged in a way to ensure adequately safeguarding against mechanical and electrical injury and deterioration due to humidity.
- The primary package is labeled as ESD sensitive component.

11. Specification History

Rev.	Drawing	Date [dd.mm.yyyy]	Remarks	Author	Checked
1	D0	10.02.2025	First issue	HH	HH